



100% Material Declaration Data Sheet PQG44

PK208 (v1.0) October 5, 2006

Material Declaration Data Sheet

Average Weight: 0.50052 g

| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|----------------------------|-----------------------|---------------------|----------------|----------------|---|-------------------------|
| Silicon Die | | | | | 0.01411 | 2.81% |
| | Silicon | 7440-21-3 | 100.00 | | 0.01411 | |
| Die Attach Material | | | | | 0.00352 | 0.70% |
| | Silver | 7440-22-4 | 70.00 | | 0.002467 | |
| | Epoxy (EP) | Trade Secret | 20.00 | | 0.000705 | |
| | Anhydride | Trade Secret | 10.00 | | 0.000352 | |
| Mold Compound | | | | | 0.34915 | 69.67% |
| | Epoxy Resin (EP) | Trade Secret | 15.00 | | 0.052373 | |
| | Silica | 60676-86-0 | 85.00 | | 0.296778 | |
| Leadframe | | | | | 0.12312 | 24.57% |
| | Copper | 7440-50-8 | 98.20 | | 0.118444 | |
| | Nickel | 7440-02-0 | 3.00 | | 0.003694 | |
| | Silicon | 7440-21-3 | 0.65 | | 0.00800 | |
| | Magnesium | 7440-95-4 | 0.15 | | 0.000185 | |
| Leadframe Plating | | | | | 0.001440 | 0.29% |
| | Silver | 7440-22-4 | 100.00 | | 0.001440 | |
| Bond Wire | | | | | 0.00101 | 0.20% |
| | Gold | 7440-57-5 | 100.00 | | 0.00101 | |
| Ext. Plating | | | | | 0.00817 | 1.76% |
| | Tin | 7440-31-5 | 100.00 | | 0.00817 | |

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Revision History

The following table shows the revision history for this document.

| Date | Revision | Revision |
|---------|----------|------------------|
| 10/5/06 | 1.0 | Initial release. |